

## Features

- Supports 100GBASE-DR1
- Lane bit rate 103.125Gb/s with PAM4
- Up to 500m transmission on SMF
- 1310nm laser and PIN receiver
- 4x25.78Gb/s with NRZ electrical interface (CAUI-4)
- I2C interface with integrated Digital Diagnostic monitoring
- QSFP28 MSA package with LC duplex connector
- Single +3.3V power supply
- Maximum power consumption 4.5 W
- Operating case temperature: 0 to +70 °C;
- Compliant to 802.3cu, SFF-8636&SFF-8679 standard
- Complies with EU Directive 2015/863/EU

## Application

- 100GBASE-DR1;
- 100G Ethernet;
- Data center / Cloud application.

## Order Information

Table 1- order information

Part No.	Data Rate	Laser	Fiber Type	Distance	Optical Interface	Temp	DDMI
UDQ1HD1S	100Gbps	1310nm	SMF	500m	SMF	0~70C	Y

## Absolute Maximum Ratings

Table 2-Absolute Maximum Ratings

Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Storage Temperature	T <sub>s</sub>	-40	-	+85	°C	
Supply Voltage	V <sub>CC</sub>	-0.5	-	+4.0	V	
Operating Relative Humidity	RH	-	-	+85	%	

## Recommended Operating Conditions

Table 3-Recommended Operating Conditions

Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Operating Case Temperature	T <sub>c</sub>	0	-	+70	°C	
Power Supply Voltage	V <sub>CC</sub>	3.13	3.3	3.47	V	
Power Supply Current	I <sub>CC</sub>	-	-	1.29	A	
Maximum Power Dissipation	P <sub>D</sub>	-	-	4.5	W	
Lane Bit Rate	BR <sub>LANE</sub>	-	106.25	-	Gb/s	With PAM4
Transmission Distance	TD	-	-	500	m	Over SMF

## Optical Characteristics

**Table 4-Optical Characteristics**

Transmitter						
Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Center Wavelength	$\lambda$	1304.5	-	1317.5	nm	
Average Launch Power	$P_{TX\_LANE}$	-2.9	-	4	dBm	1
$OMA_{outer}$	OMA	-0.8	-	4.2	dBm	
Launch power in $OMA_{outer}$ minus TDECQ	OMA -	-2.2	-	-	dB	$ER \geq 5$ dB
	TDECQ	-1.9	-	-	dB	$ER < 5$ dB
Transmitter and dispersion eye closure for PAM4 (TDECQ)	TDECQ	-	-	3.5	dB	
Average Output Power (Laser Turn off)	$P_{OUT-OFF}$	-	-	-15	dBm	
Side Mode Suppression Ratio	SMSR	30	-	-	dB	
Extinction Ratio	ER	3.5	-	-	dB	
Receiver						
Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Center Wavelength	$\lambda$	1304.5	-	1317.5	nm	
Damage threshold	$P_{damage}$	5	-	-		2
Average Rx Power	$P_{RX\_LANE}$	-5.9	-	4	dBm	3
Receiver power ( $OMA_{outer}$ )	$P_{OMA\_LANE}$	-	-	4.2	dBm	
Receiver sensitivity ( $OMA_{outer}$ )	$SEN_{OMA}$	8023cu_D1p0 Equation (140-1)			dBm	4
Stressed receiver sensitivity ( $OMA_{outer}$ )	$SRS_{OMA}$	-	-	-1.9	dBm	5

Notes:

1. The optical power is launched into SMF.
2. The receiver shall be able to tolerate, without damage, continuous exposure to an optical input signal having this average power level. The receiver does not have to operate correctly at this input power.
3. Average receive power, each lane (min) is informative and not the principal indicator of signal strength.
4. Receiver sensitivity ( $OMA_{outer}$ ), each lane (max) is informative and is defined for a transmitter with SECQ up to 3.4 dB
5. Measured with conformance test signal at TP3 (see 140.8) for the BER specified in 140.1.1.

## Digital Diagnostics

**Table 5-Digital Diagnostics**

Parameter	Range	Accuracy	Unit	Calibration
Temperature	0 to 70	$\pm 3$	$^{\circ}C$	Internal
Voltage	0 to $V_{CC}$	10%	V	Internal
Tx Bias Current	0 to 100	10%	mA	Internal
Tx Output Power	-2.9 to 4	$\pm 3$	dBm	Internal
Rx Input Power	-5.9 to 4	$\pm 3$	dBm	Internal

## Electrical Characteristics

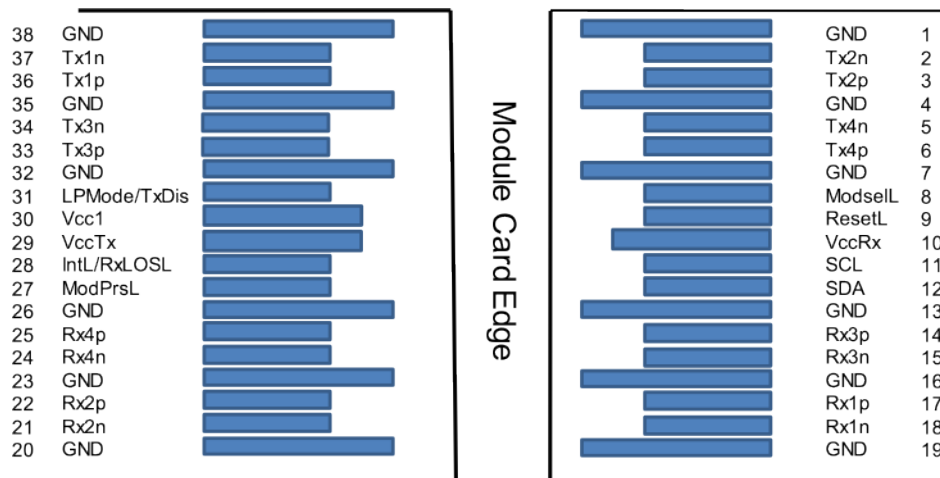
High-Speed Signal: Compliant to CAUI-4 (IEEE 802.3bm)

Low-Speed Signal: Compliant to SFF-8679.

Table 6-Electrical Characteristics

Transmitter (Module Input)						
Parameter	Symbol	Min.	Typical	Max.	Unit	Notes
Differential Data Input Amplitude	$V_{IN,P-P}$	85	-	900	mVpp	
Differential Termination Mismatch		-	-	10	%	
LPMoDe, Reset and ModSelL, V in low	$V_{IL}$	-0.3	-	0.8	V	
LPMoDe, Reset and ModSelL, V in high	$V_{IH}$	2.0	-	$V_{CC}+0.3$	V	
Receiver (Module Output)						
Differential Data Output Amplitude	$V_{OUT,P-P}$	200	-	900	mVpp	
Differential Termination Mismatch (1MHZ)		-	-	10	%	
Transition time, 20% to 80%	$T_r T_f$	12			ps	
ModPrsL and IntL, V out low	$V_{OL}$	0	-	0.4	V	
ModPrsL and IntL, V out high	$V_{OH}$	$V_{CC}-0.5$	-	$V_{CC}+0.3$	V	

## Pin Definitions



Top Side  
Viewed From Top

Bottom Side  
Viewed From Bottom

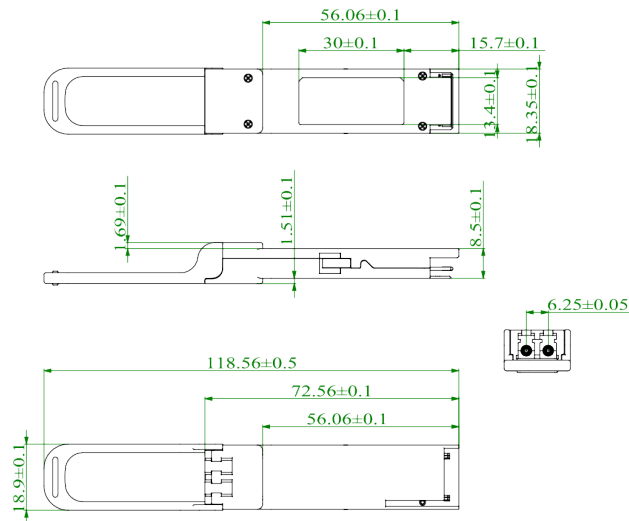
PIN	Logic	Symbol	Description	Plug Seq.	Notes
1		GND	Ground	1	1
2	CML-I	Tx2n	Transmitter Inverted Data Input	3	
3	CML-I	Tx2p	Transmitter Non-Inverted Data output	3	
4		GND	Ground	1	1
5	CML-I	Tx4n	Transmitter Inverted Data Input	3	
6	CML-I	Tx4p	Transmitter Non-Inverted Data output	3	
7		GND	Ground	1	1
8	LVTLL-I	ModSelL	Module Select	3	
9	LVTLL-I	ResetL	Module Reset	3	

10		VccRx	+ 3.3V Power Supply Receiver	2	2
11	LVC MOS-I/O	SCL	2-Wire Serial Interface Clock	3	
12	LVC MOS-I/O	SDA	2-Wire Serial Interface Data	3	
13		GND	Ground	1	
14	CML-O	Rx3p	Receiver Non-Inverted Data Output	3	
15	CML-O	Rx3n	Receiver Inverted Data Output	3	
16		GND	Ground	1	1
17	CML-O	Rx1p	Receiver Non-Inverted Data Output	3	
18	CML-O	Rx1n	Receiver Inverted Data Output	3	
19		GND	Ground	1	1
20		GND	Ground	1	1
21	CML-O	Rx2n	Receiver Inverted Data Output	3	
22	CML-O	Rx2p	Receiver Non-Inverted Data Output	3	
23		GND	Ground	1	1
24	CML-O	Rx4n	Receiver Inverted Data Output	3	
25	CML-O	Rx4p	Receiver Non-Inverted Data Output	3	
26		GND	Ground	1	1
27	LV TTL-O	ModPrsL	Module Present	3	
28	LV TTL-O	IntL/Rx_LOS	Interrupt/Rx_LOS	3	
29		VccTx	+3.3 V Power Supply transmitter	2	2
30		Vcc1	+3.3 V Power Supply	2	2
31	LV TTL-I	LPMoDe/TxDIS	Low Power Mode/Tx_Disable	3	
32		GND	Ground	1	1
33	CML-I	Tx3p	Transmitter Non-Inverted Data Input	3	
34	CML-I	Tx3n	Transmitter Inverted Data Output	3	
35		GND	Ground	1	1
36	CML-I	Tx1p	Transmitter Non-Inverted Data Input	3	
37	CML-I	Tx1n	Transmitter Inverted Data Output	3	
38		GND	Ground	1	1

Note 1: GND is the symbol for signal and supply (power) common for the QSFP28 module. All are common within the QSFP28 module and all module voltages are referenced to this potential unless otherwise noted. Connect these directly to the host board signal-common ground plane.

Note 2: Vcc Rx, Vcc1 and Vcc Tx are the receiver and transmitter power supplies and shall be applied concurrently. Requirements defined for the host side of the Host Edge Card Connector are listed in MSA. The connector pins are each rated for a maximum current of 1000 mA.

## Mechanical Dimension



## Warnings

**Handling Precautions:** This device is susceptible to damage as a result of electrostatic discharge (ESD). A static free environment is highly recommended. Follow guidelines according to proper ESD procedures.

**Laser Safety:** The Moduletek family Transceiver uses a semiconductor laser system and is a laser class 1 product acc. FDA, complies with 21CFR1040. 10 and 1040.11. Also this product is a laser class 1 product acc. IEC 60825-1.